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Chou et al.

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(54) **BRIDGE RECTIFIER PACKAGE WITH HEAT SINK**

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(73) Assignee: **Vishay General Semiconductor LLC**, Hauppauge, NY (US)

(**) Term: **14 Years**

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(51) **LOC (8) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** D13/179; 165/80.3, 104.33, 151, 122, 185; 257/706, 257/707, 718–722, 177, 347; 361/687, 695, 361/697, 700, 702, 704, 709, 710, 711, 719
See application file for complete search history.

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(57) CLAIM

We claim the ornamental design for a new bridge rectifier package with heat sink, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view, left top of a first embodiment of a new bridge rectifier package with heat sink;

FIG. **2** is a top view thereof;

FIG. **3** is a bottom view thereof;

FIG. **4** is a left of front view thereof;

FIG. **5** is a right of front view thereof;

FIG. **6** is a front view thereof; and

FIG. **7** is a back view thereof;

FIG. **8** is a perspective view, left top of an second embodiment of a new bridge rectifier package with heat sink;

FIG. **9** is a top view thereof;

FIG. **10** is a bottom view thereof;

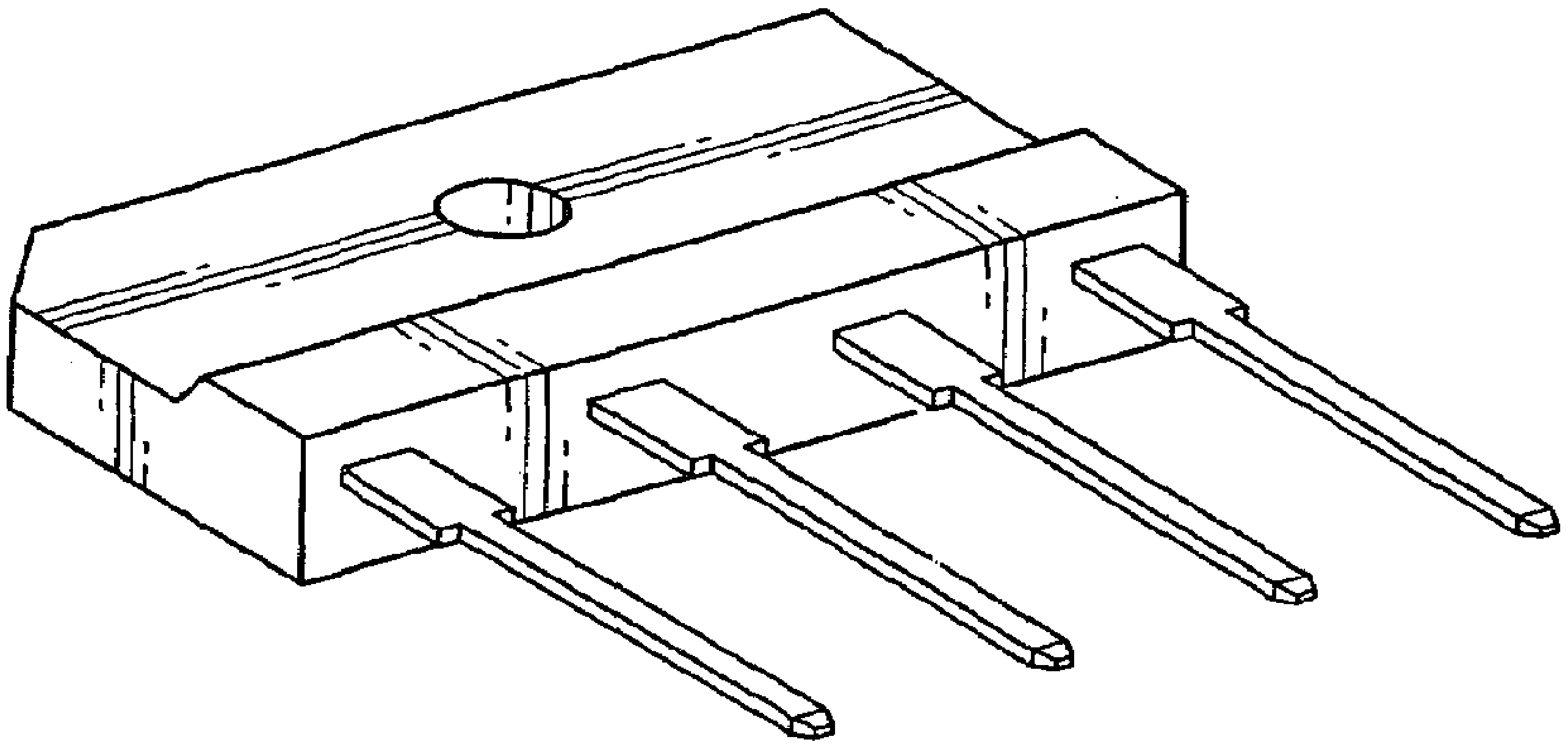
FIG. **11** is a left of front view thereof;

FIG. **12** is a right of front view thereof;

FIG. **13** is a front view thereof; and,

FIG. **14** is a back view thereof.

1 Claim, 4 Drawing Sheets



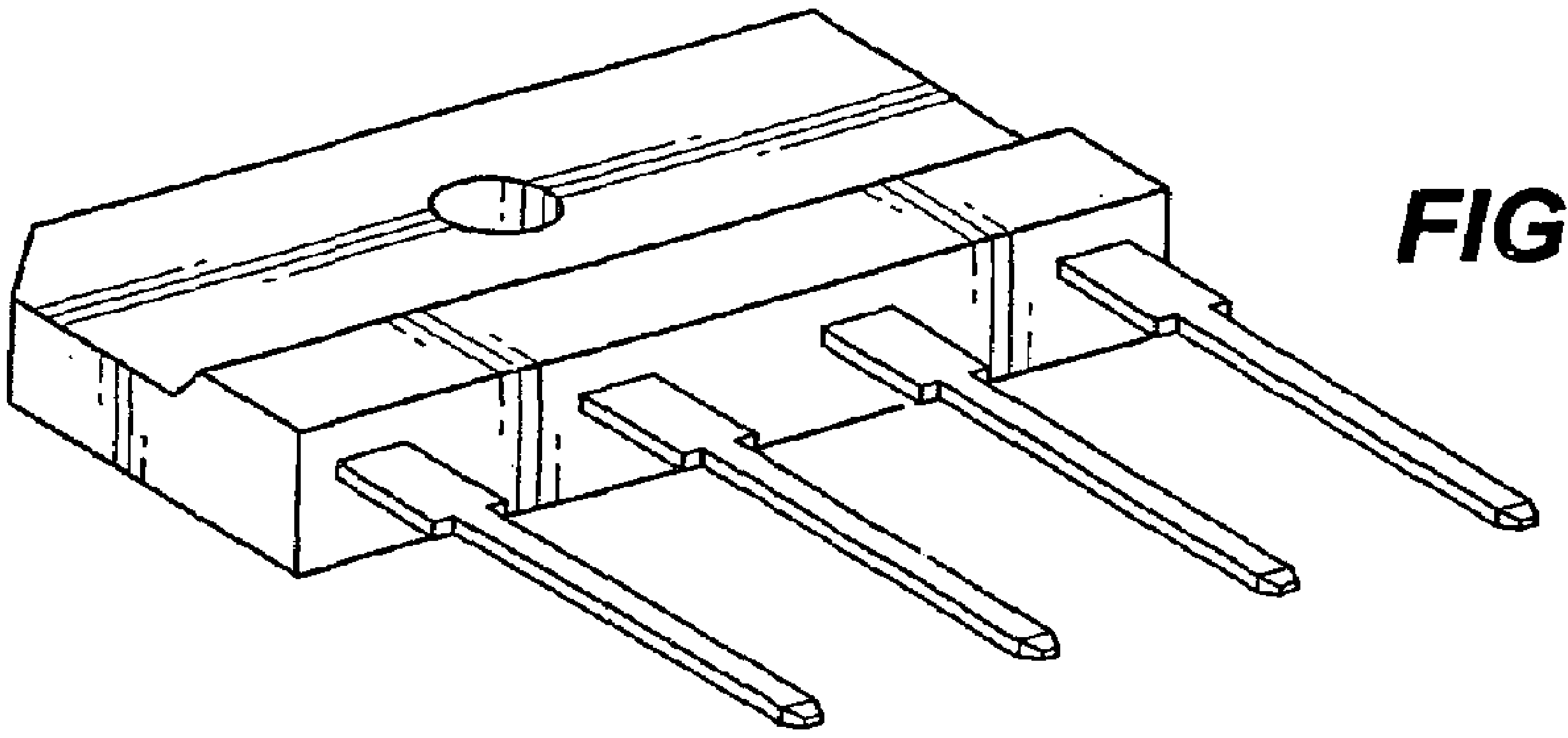


FIG. 1

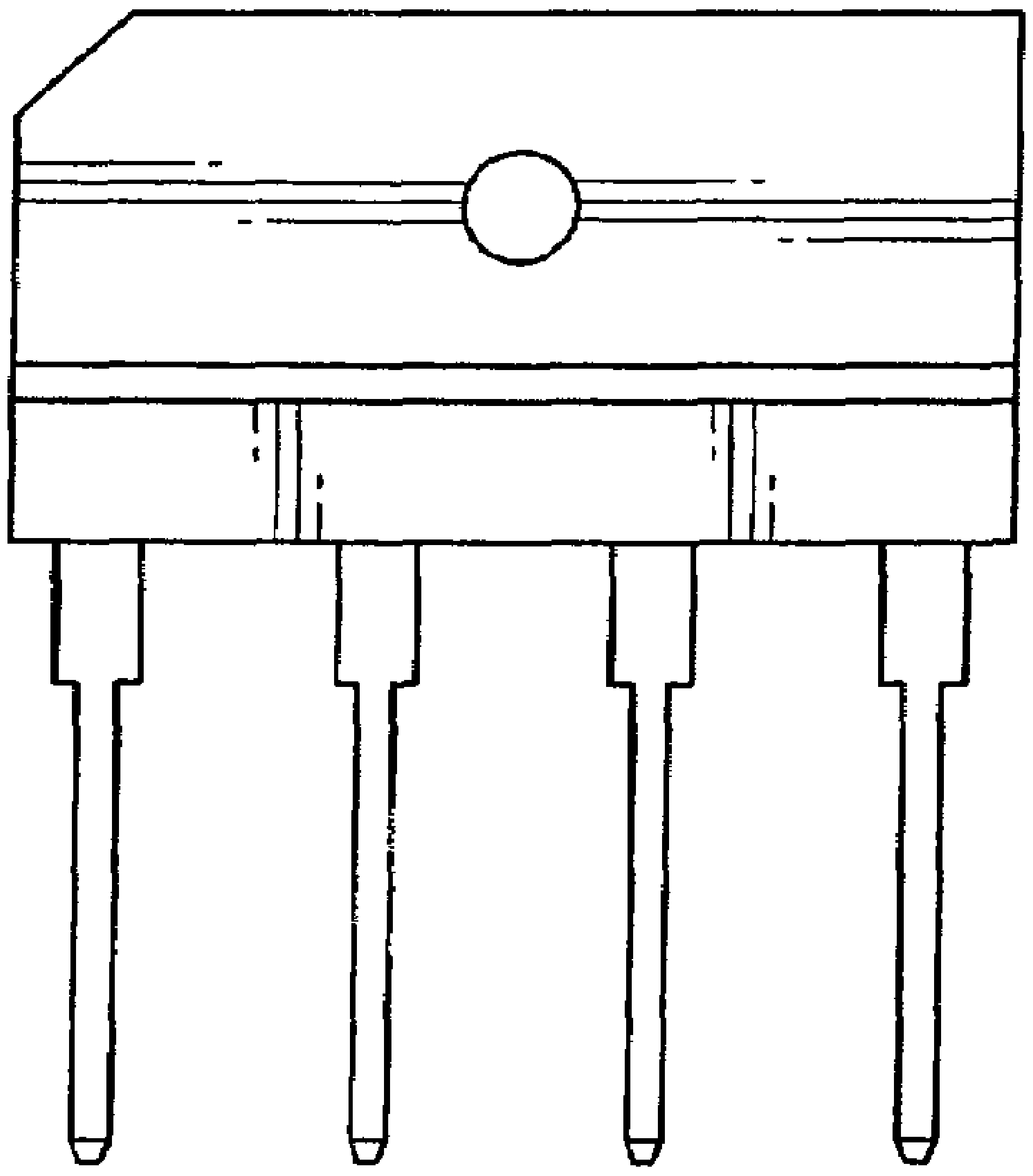


FIG. 2

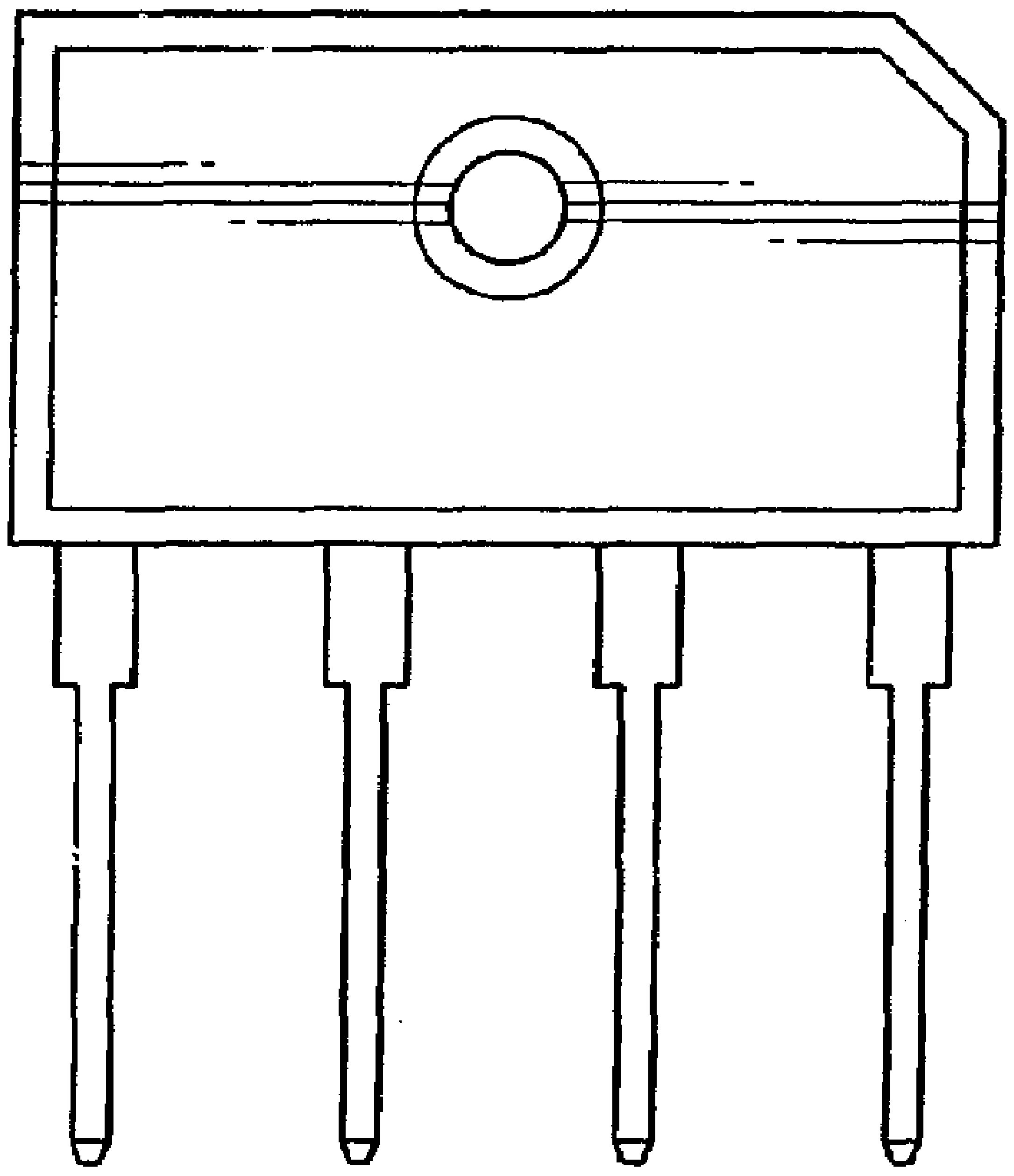


FIG. 3

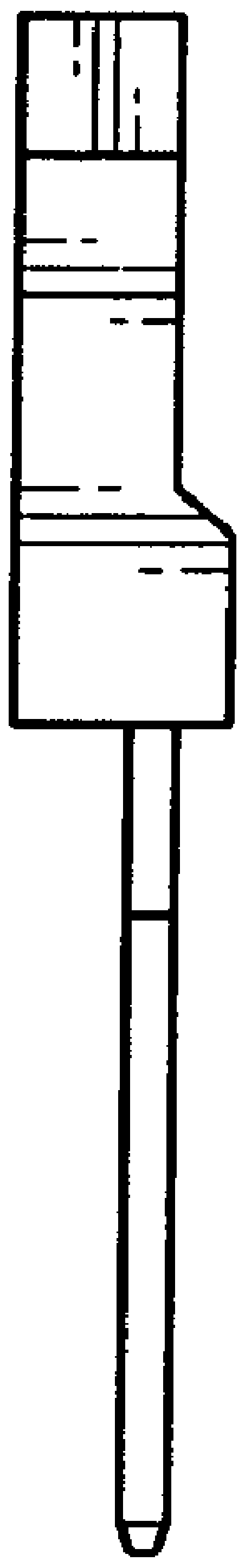


FIG. 4

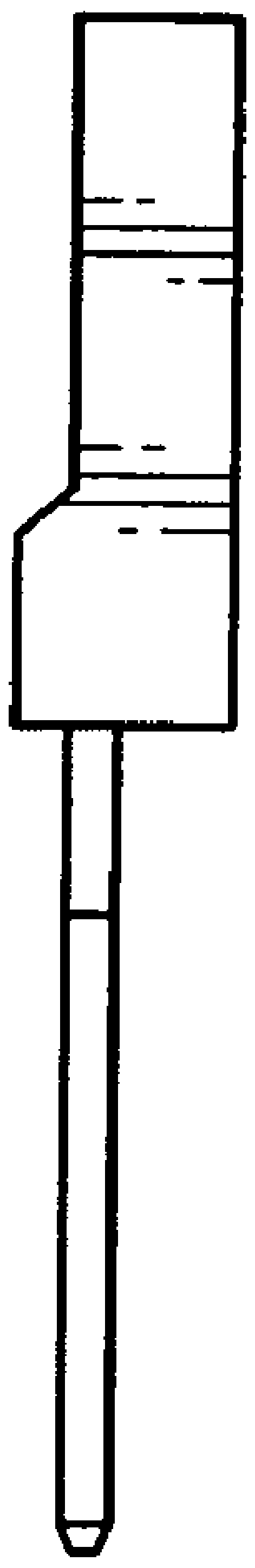


FIG. 5

FIG. 6

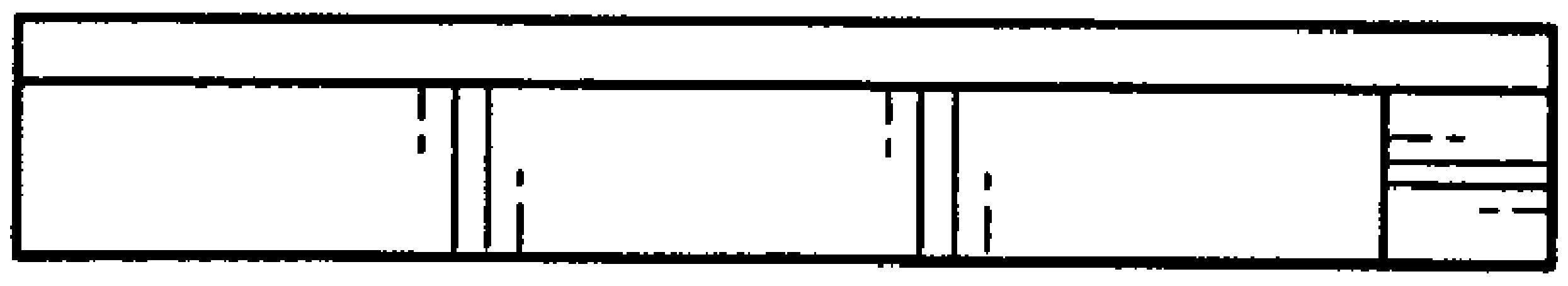


FIG. 7

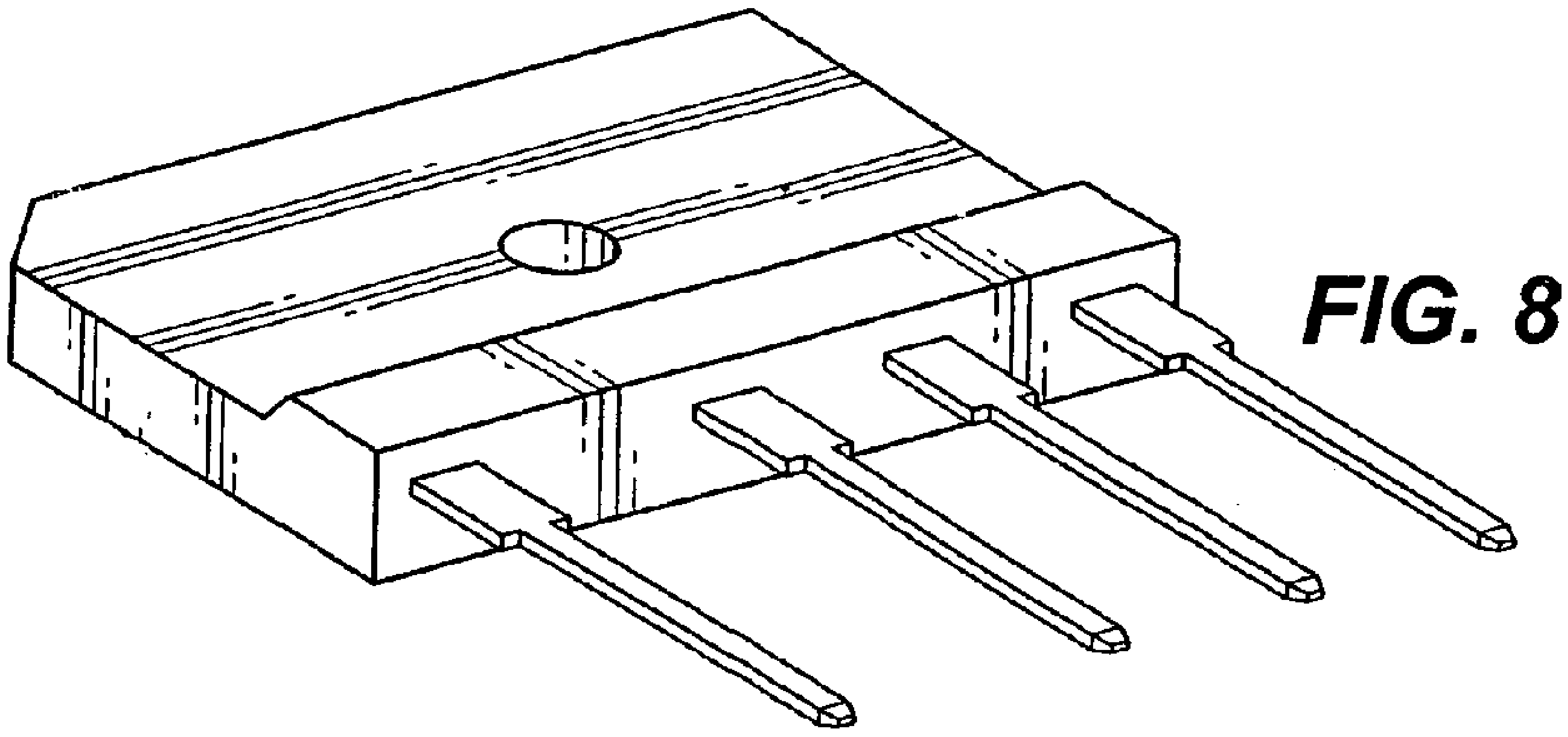


FIG. 8

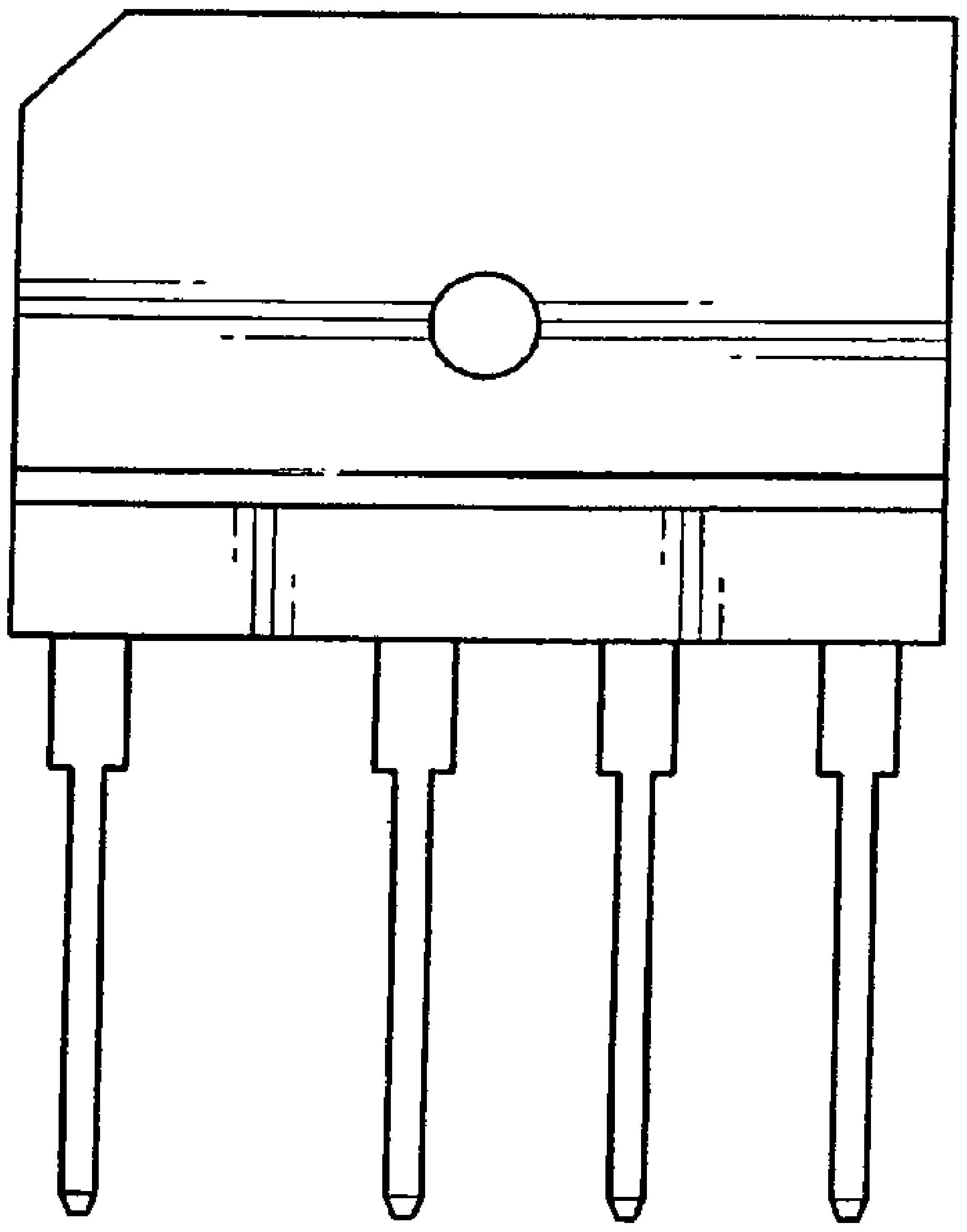


FIG. 9

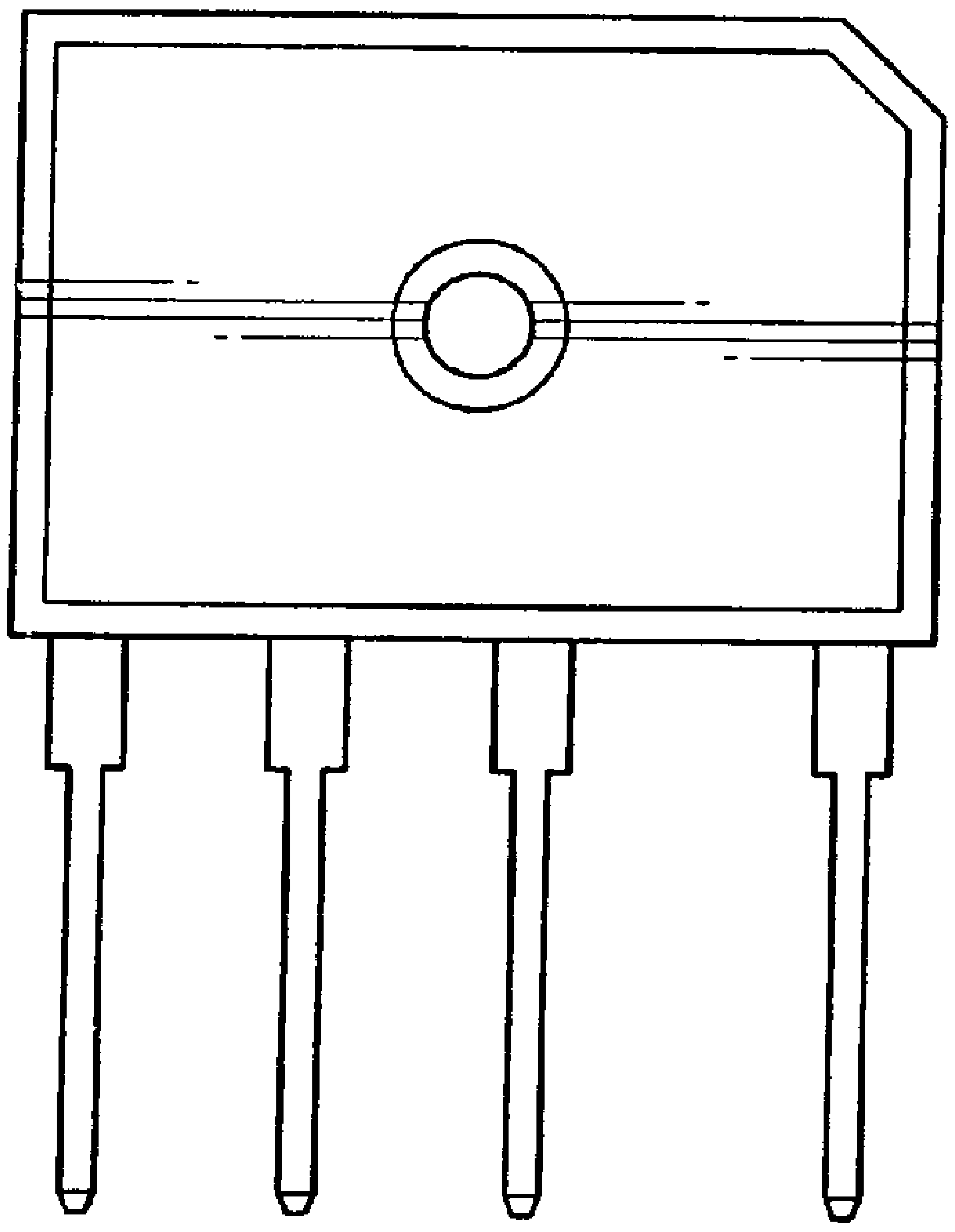


FIG. 10

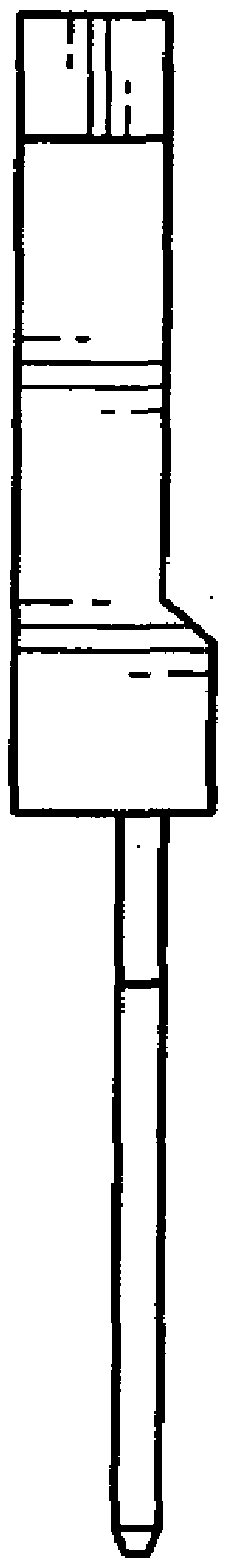


FIG. 11

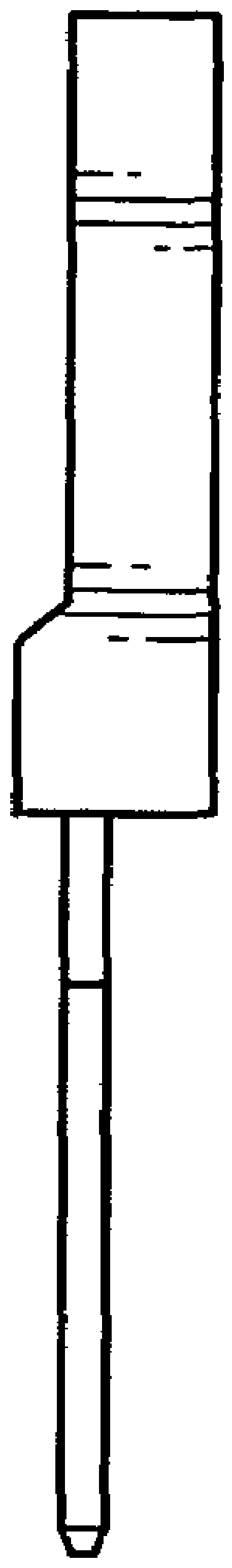


FIG. 12

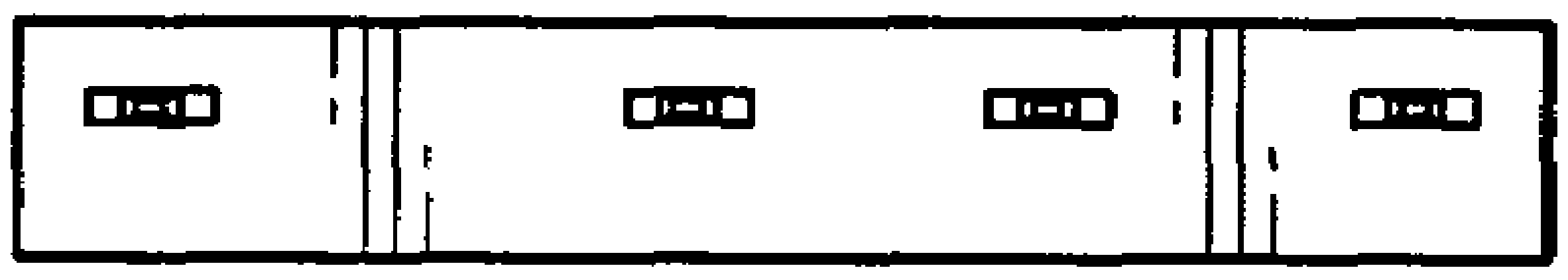


FIG. 13

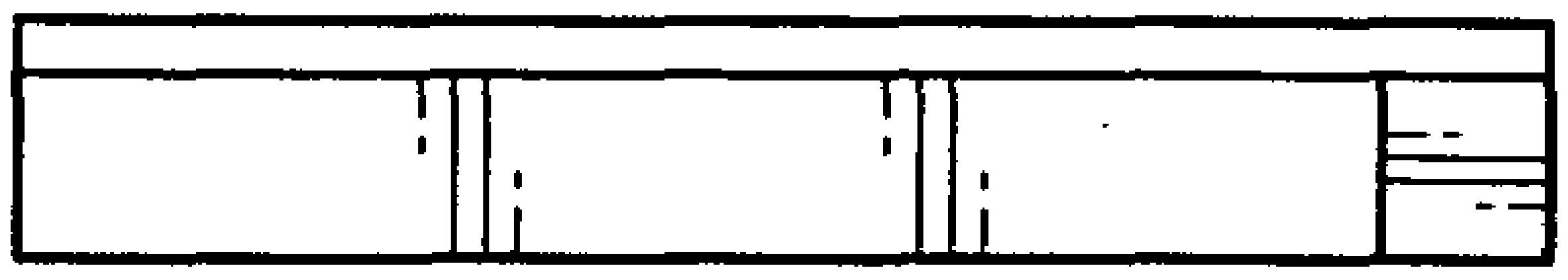


FIG. 14